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ABSTRACT OF THE DISCLOSURE

5 An apparatus for removing fluorinated and chlorinated compounds contained in waste gas streams from semiconductor etch and deposition processes. The apparatus has a treatment chamber in which a plurality of liquid films are formed to absorb the fluorinated and chlorinated compounds 10 contained in the waste gas streams that pass through the liquid films. The apparatus includes a tank for receiving the mixture of the absorbed fluorinated and chlorinated compounds and the liquid, and a dehumidifying device for stabilizing and dehumidifying the humidified waste gas 15 streams.